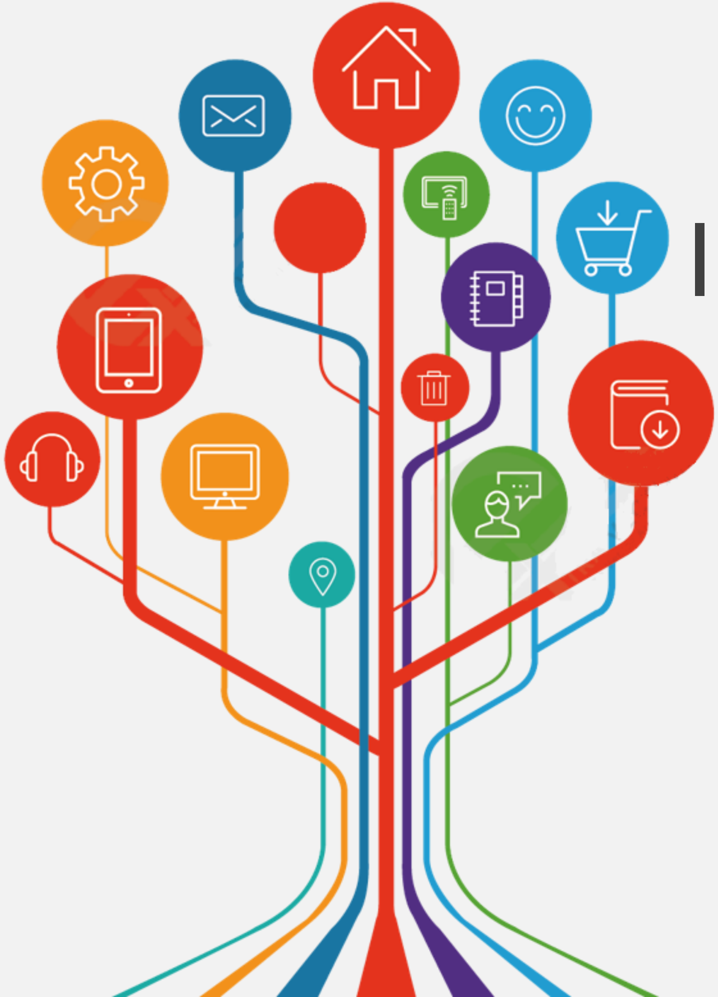


INVESTOR CONFERENCE

HOWTEH TECHNOLOGY CO., LTD.

Presenter： Alex Chuang　　Date： 2025/12/02

Safe Harbor Notice

The Group has not announced any financial forecasts. Statements made in this investor conference regarding operating results, financial status, or business outlook may involve forward-looking statements that are subject to known or unknown risks, uncertainties, and other factors.

Except as required by applicable laws, the Company undertakes no obligation to disclose, update, or revise any forward-looking statements or projections, whether as a result of new information, future events, or any other circumstances.

All financial information contained in this presentation has been prepared in accordance with the International Financial Reporting Standards (IFRS).

議程
AGENDA

1. Company Overview
2. Industry Environment & Market Trends
3. Operational Highlights
4. Financial Performance
5. Strategic Priorities & Future Outlook
6. Q&A

01

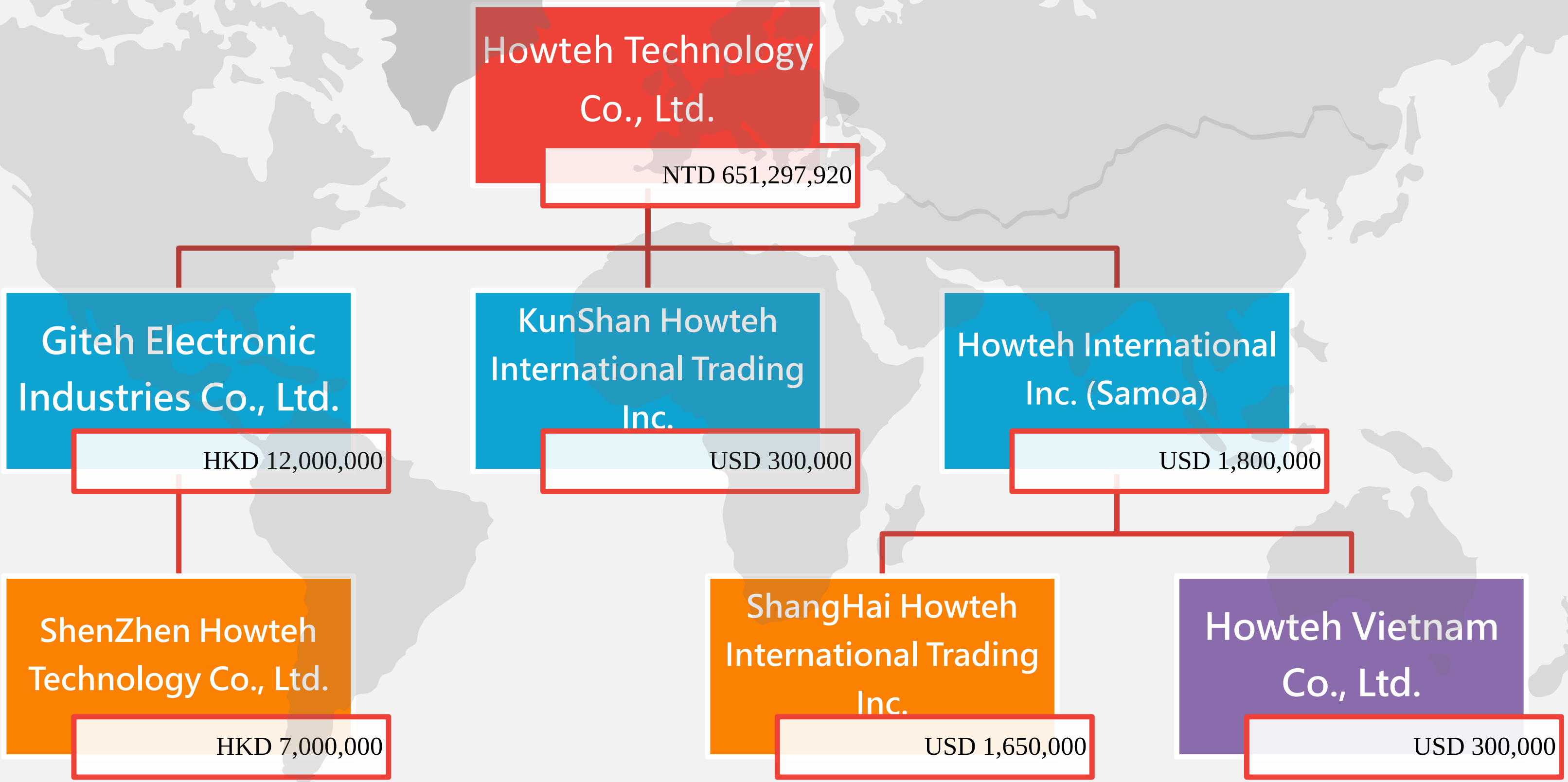
Company Overview

- Basic Information
- Service Scope
- Organizational Structure & Global Presence
- Major Products

Basic Information

Established	September 1978
Employees	105 employees
IPO Date	March 2004
Chairman	Bruce Chen
Capital	NT$651 million
Products	Electronic components and equipment

Organizational Structure & Global Presence



- Howteh Technology Co., Ltd.
NTD 651,297,920
  - Giteh Electronic Industries Co., Ltd.
HKD 12,000,000
    - ShenZhen Howteh Technology Co., Ltd.
HKD 7,000,000
  - KunShan Howteh International Trading Inc.
USD 300,000
  - Howteh International Inc. (Samoa)
USD 1,800,000
    - ShangHai Howteh International Trading Inc.
USD 1,650,000
    - Howteh Vietnam Co., Ltd.
USD 300,000

Service Scope: Electronic Components

IT 產業

Information Technology

☐ Desktop computers / Notebook computers / Tablet devices

☐ Computer peripheral equipment

消費性電子產業

Consumer Electronic

☐ TWS Earbuds / Smart Speakers

☐ Electronics for Electric Vehicles (EV Cars & EV Motorcycles)

☐ Smart Educational Tablets

AI 產業

AI Industry

☐ Home Cleaning Robots

☐ AR Smart Glasses (Augmented Reality)

☐ AI meeting transcription and analytics devices

通訊產業

Communicate

☐ Mobile device applications

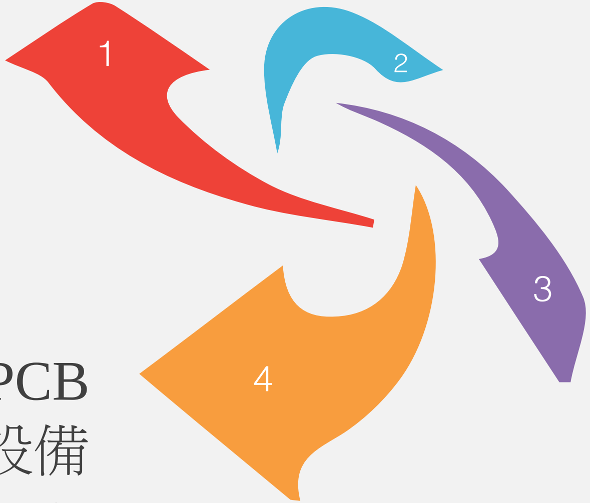
☐ Optical communication

☐ Networking Applications

☐ Servers

☐ Thunderbolt 5

Service Scope: Equipment



半導體 Semiconductor
觸控面板 Touch Panel

太陽能產業Solar
綠能產業 Green

化學材料
Chemical Material

印刷電路板設備PCB
AI覆晶載板設備
AI Flip-Chip Substrate

Key Suppliers and Products

Japan Aviation Electronics
Connectors

Sumitomo
Cable

Knowles
BA unit

Syntiant
Microphone
NDP

Awinic
Analog Power Amp IC

eEver
Interface IC

Lite-On
Optocoupler、Ambient Light Sensor

Potens
MOSFET

Raffar
LED Driver IC

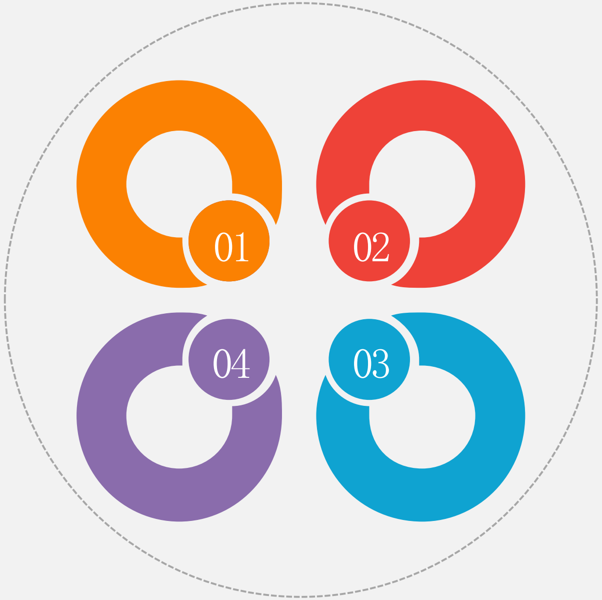
Canon Machinery Inc.
Cutting Machines for Flip-Chip & IGBT Substrates (Solder Ball / Nano-Silver Thermocompression Bonding

02

Industry Environment & Market Trends

- Product trends and technological developments
- Global market movements
- Geopolitical risks and responses
- Competitive advantages

Product trends and technological developments



1

AI NDP + Algorithm + Sensor Technologies

☐ Powerful noise-reduction, low-power consumption, and advanced voice-pickup algorithmsEnhanced imaging and acoustic recognition for improved human-voice and object-recognition capabilitiesAccelerating the adoption of edge-AI devices

2

High-Speed Transmission and Signal/Power Integrity (SI/PI) Optimization

☐ Developing TBT5, the highest-speed consumer transmission interface

☐ Supports up to 120G maximum bandwidth, covering data, power, and video transmission

☐ Unified USB Type-C interface aligns with EU regulatory requirements; major notebook clients are driving its widespread adoption.

3

Lens Module Focused Solutions

☐ Promotion of ISP, MIC, DC-DC, and Connector solutions for notebook applications

☐ OIS solutions for smartphone cameras, including triple-camera central layouts and motor-driver solutions

☐ Development of image-driver and power-management ICs for automotive cameras and AR-glasses optics

4

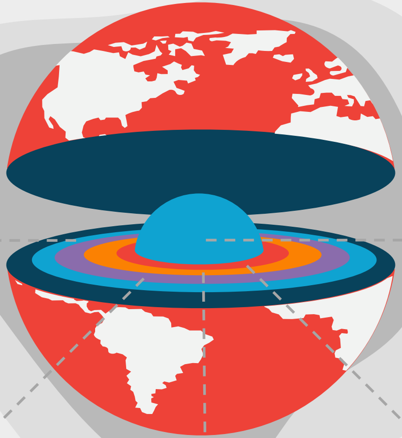
Precision Board-to-Board / I-O Connector Technologies

☐ Developing higher-density and higher-speed board-to-board connectors.

☐ Focusing on rugged laptop interfaces and keyboard connector development.

☐ Customized development of in-vehicle cables and connectors.

Global market movements



AI is driving the expansion of HMI (Human–Machine Interface) demand

Flagship phones and AI devices are adopting higher-spec sensors.

Accelerated adoption of advanced imaging and acoustic sensing products.

Long-Term Uptrend in High-Speed Connectivity and Data Transmission Demand

Applications such as 5G, AI PCs, and cloud data centers are driving increased usage of high-speed transmission peripherals.

Continue developing higher-spec connectors and cables

Rising Demand in Consumer Electronics

Changes in global working patterns are driving higher usage of docking stations and cables for high-end laptops.

Technological advancements in home cleaning robots and related devices.

AI computing power continues to surge

Rising demand for advanced AI substrates

Development of glass substrates and synthetic-diamond wafer technologies

Steady Growth in Automotive Electronics

The consumer automotive market emphasizes high-reliability connectors and power modules.

Geopolitical risks and responses

01.

Rising cross-strait tensions

02.

The U.S.–China technology war

03.

Political risks associated with principals’ geographic locations and the southbound shift of the supply chain

Howteh must build a resilient cross-border distribution and supply chain through supplier diversification, multinational logistics deployment, and customer base diversification to mitigate geopolitical impacts and maintain operational stability.

Competitive advantages

Key Strengths

Products

Comprehensive product solutions supported by diverse supplier resources

Customers

Long-term partnerships with key customers

Supply Chain

Robust supply readiness and rapid response

03

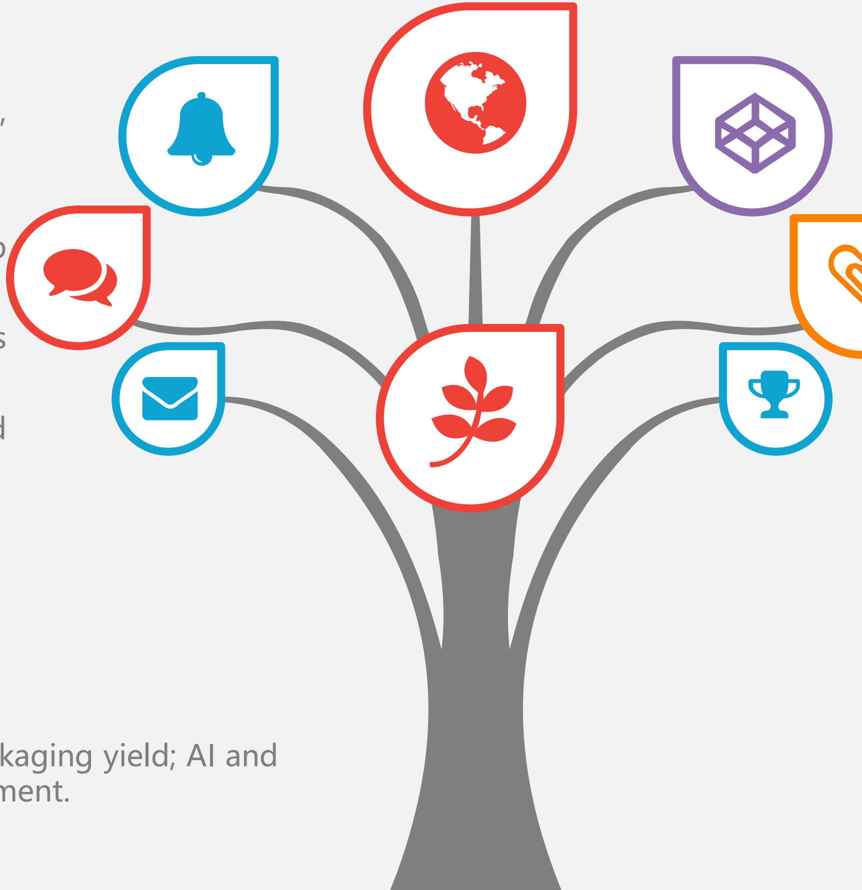
Operational Highlights

- Overview of business segment performance
- Key operating results

Overview of business segment performance

Electronic Components

- Flagship smartphones adopted OIS ICs, driving revenue growth.
- TBTS cables entered DHL’s premium laptop docking products, boosting revenue and margin.
- Consumer AI devices are growing rapidly across categories.
- SEI high-speed FFC adopted in HP’s next-generation laptop internal connections.
- Strong memory demand; deeper collaboration with SMI expands penetration across markets.
- Stable growth in JAE connector demand across consumer and automotive applications.



Equipment

Introduced Canon solder ball flattening equipment to enhance packaging yield; AI and advanced packaging continue to drive demand for substrate equipment.

Key operating results

Camera Module Solutions

OIS IC, microphones, DC-DC, MOSFETs, and connectors for camera modules in automotive, laptop, smartphone, and conferencing applications.

Edge AI Solutions

Includes NDP, sensors, analog ICs, and connectors to enable low-power, noise-reduction, and slim designs.

AI High-End Substrate Demand

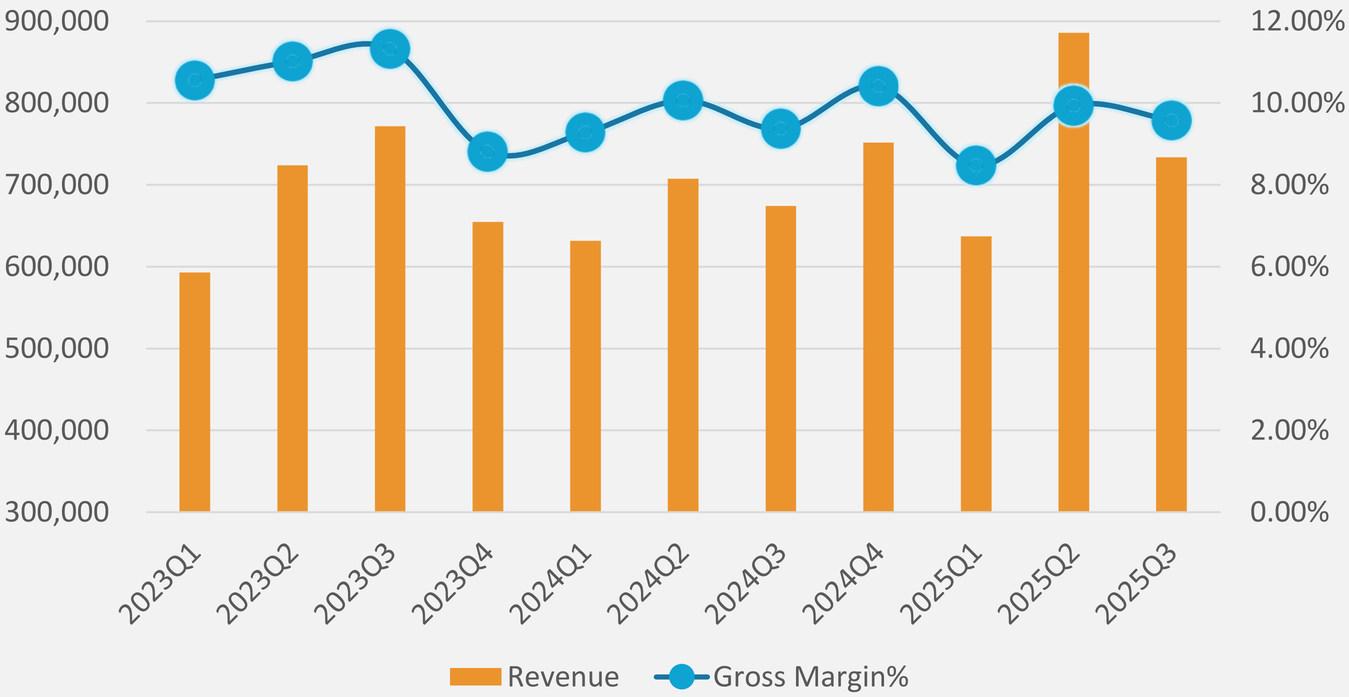
Canon’s bump-flattening and glass-substrate dicing systems meet rising AI substrate demand.

04

Financial Performance

- Revenue and gross margin trends
- Operating Cash Cycle
- EPS & Dividend Policy

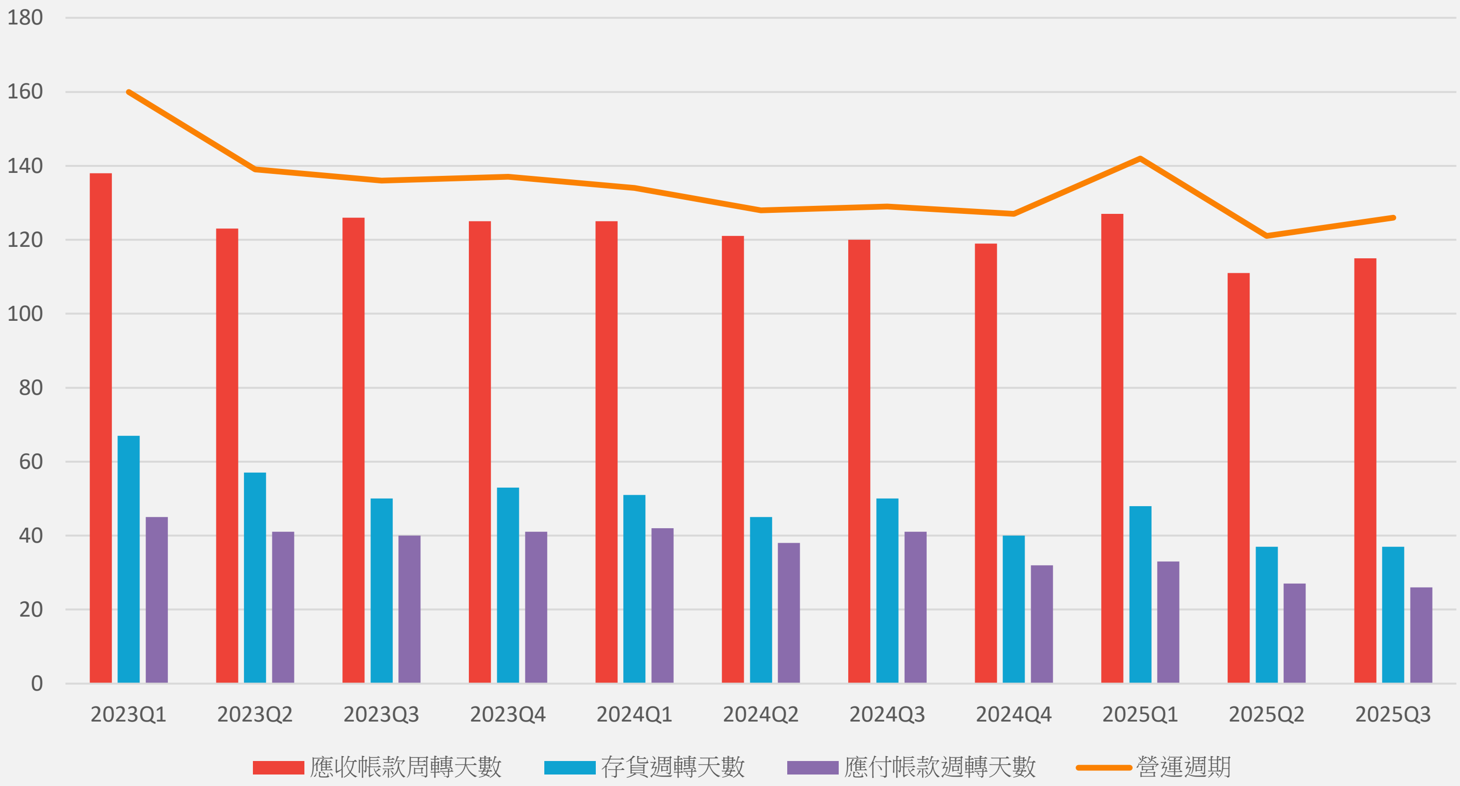
Three-Year Revenue and Gross Margin Trends



Revenue shows steady growth.

Gross margin remains within the 9% – 11% range.

Operating Cash Cycle

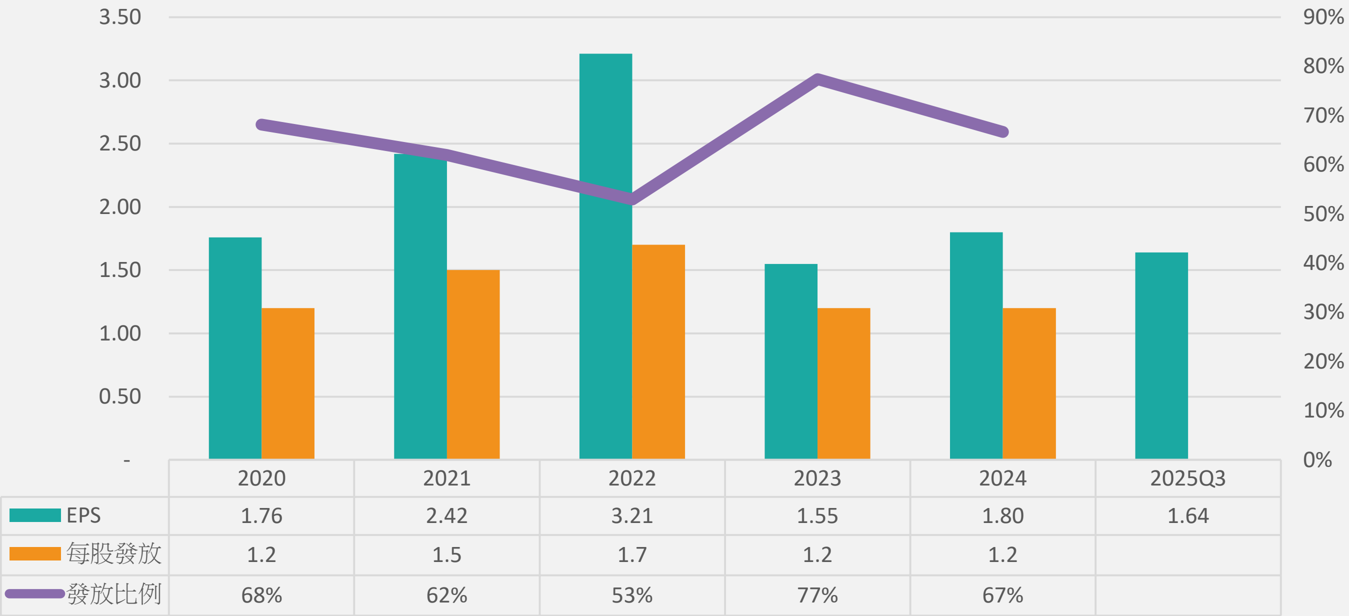


Days of operating cycle have gradually decreased.

The Company’s overall working capital efficiency continues to improve.

Cash collection has accelerated, resulting in stronger liquidity and faster turnover.

Five-Year EPS & Dividend Policy



	2020	2021	2022	2023	2024	2025Q3
🟩 EPS	1.76	2.42	3.21	1.55	1.80	1.64
🟧 每股發放	1.2	1.5	1.7	1.2	1.2	
▬ 發放比例	68%	62%	53%	77%	67%	

- ☐ Despite recent macro-environment challenges, HOWTEH continues to deliver positive earnings performance.
- ☐ A stable dividend policy provides shareholders with long-term and predictable returns.

05

Strategic Priorities & Future Outlook

- Operational strategic direction
- Future market outlook and growth opportunities

Operational strategic direction

Launch of New Product Lines; Establishment of the KPM Team

KPM talent allocation with newly formed PM and FAE teams

Product development driven by solving customer pain points

Edge AI ecosystem solution offerings

Integrated IC solution development

Deepening engagement with key accounts

☐ Established the KAD Business Unit in Taiwan

☐ Achieved strong traction in the automotive market

☐ Enhanced engagement with key notebook clients

Winning New Line Cards

☐ Expanded promotion for SG Micro, Awinic, and JAE

☐ New customer wins and Edge-AI application opportunities

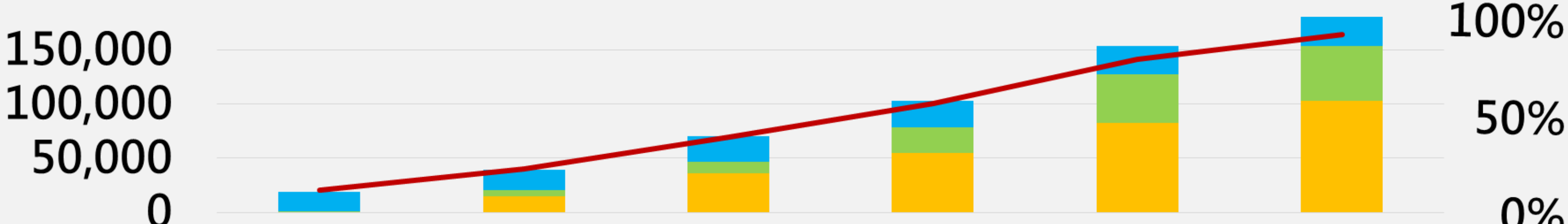
Organizational Optimization

Talent review to recruit key personnel and cultivate a seed team.

Future market outlook and growth opportunities

AI NB penetration has grown slower than expected
Market share is projected to exceed 90% by 2028

AI NB shipment trends and forecast by platform, 2023–2028

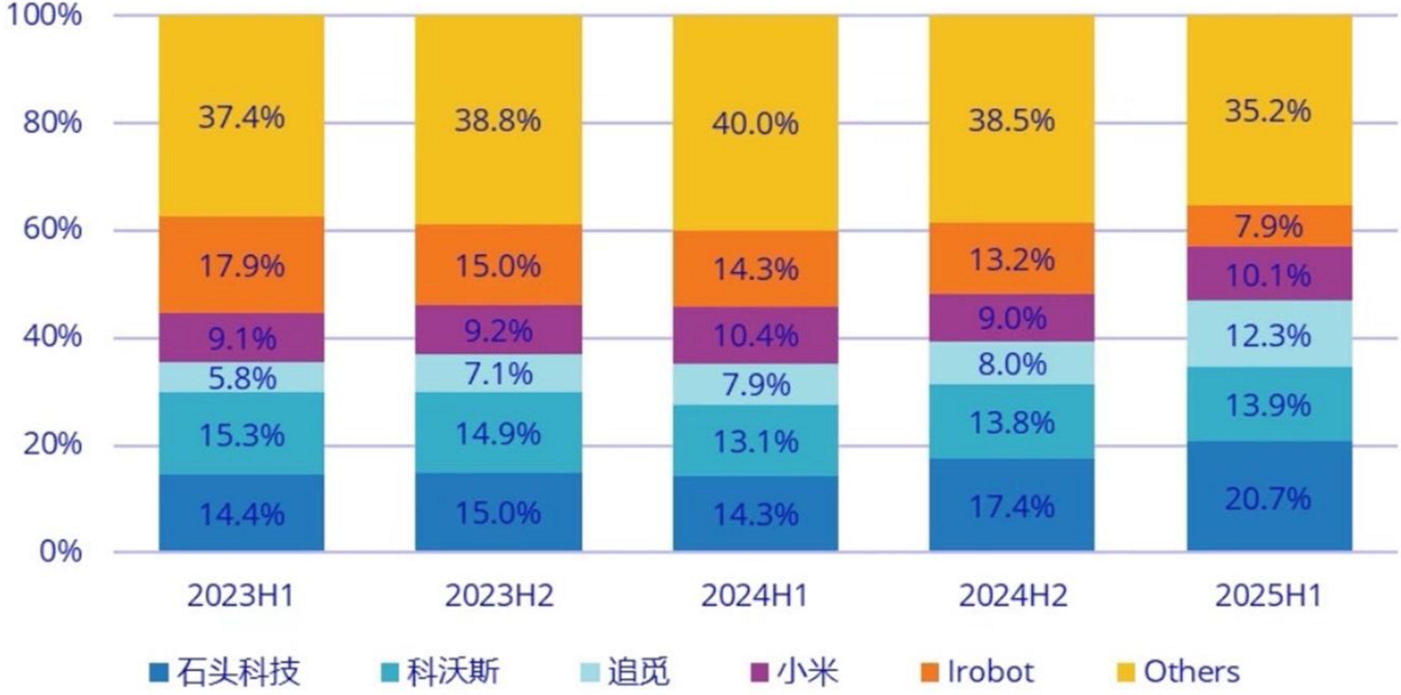


	2023	2024	2025(f)	2026(f)	2027(f)	2028(f)
🟦 Arm架構	17,946	18,450	23,353	24,224	26,130	27,101
🟩 AMD	905	5,436	11,234	23,657	44,652	50,678
🟨 Intel	-	15,243	35,779	55,199	82,925	102,892
AI NB Total	18,850	39,129	70,366	103,079	153,708	180,670
Total YoY	-18.7%	107.6%	79.4%	46.5%	49.1%	17.5%
— AI NB Share	11.4%	22.3%	38.8%	56.0%	78.6%	91.2%

資料來源：DIGITIMES，2025/10

IDC

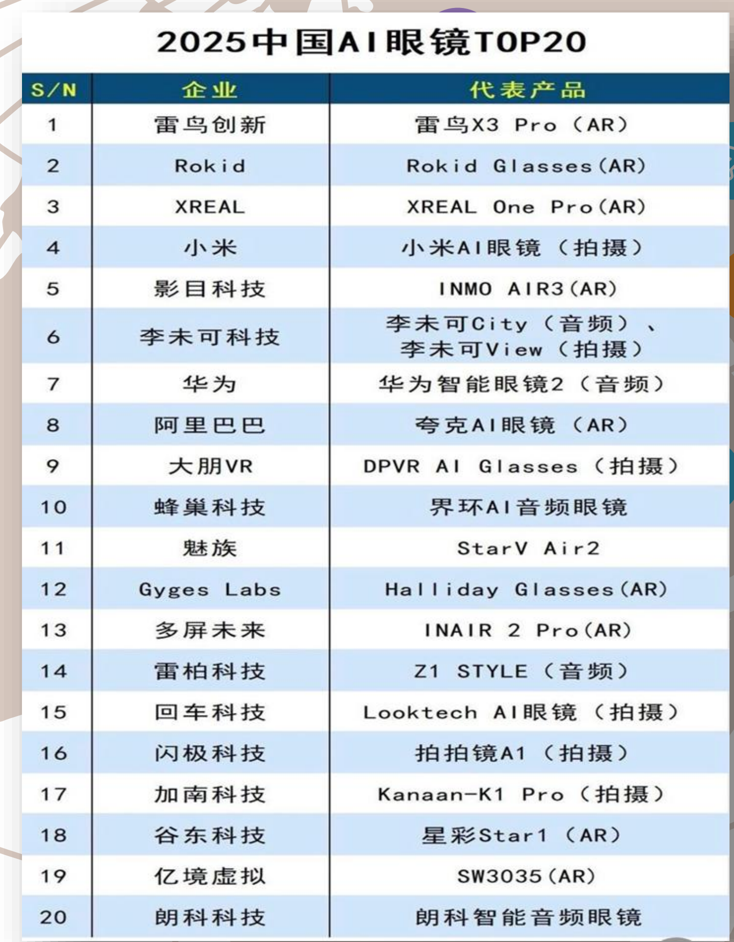
全球智能家居扫地机器人主要厂商市场份额（台数）,2023H1-2025H1



来源：IDC，2025

2024-2030年AR眼镜出货量预估

Source: TrendForce, Sept. 2025



2025中国AI眼镜TOP20

S/N	企业	代表产品
1	雷鸟创新	雷鸟X3 Pro（AR）
2	Rokid	Rokid Glasses（AR）
3	XREAL	XREAL One Pro（AR）
4	小米	小米AI眼镜（拍摄）
5	影目科技	INMO AIR3（AR）
6	李未可科技	李未可City（音频）、 李未可View（拍摄）
7	华为	华为智能眼镜2（音频）
8	阿里巴巴	夸克AI眼镜（AR）
9	大朋VR	DPVR AI Glasses（拍摄）
10	蜂巢科技	界环AI音频眼镜
11	魅族	StarV Air2
12	Gyges Labs	Halliday Glasses（AR）
13	多屏未来	INAIR 2 Pro（AR）
14	雷柏科技	Z1 STYLE（音频）
15	回车科技	Looktech AI眼镜（拍摄）
16	闪极科技	拍拍镜A1（拍摄）
17	加南科技	Kanaan-K1 Pro（拍摄）
18	谷东科技	星彩Star1（AR）
19	亿境虚拟	SW3035（AR）
20	朗科科技	朗科智能音频眼镜

Source： eNet & Ciweek 2025-08

Q & A

Please state your affiliation or organization name before asking questions.

HOWTEH will make subsequent disclosures on our official website and MOPS should any matters discussed involve material information requiring public announcement under applicable laws and regulations.